## Intel - 5CEFA7M15C7N Datasheet





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#### Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

#### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Active
Number of LABs/CLBs	56480
Number of Logic Elements/Cells	149500
Total RAM Bits	7880704
Number of I/O	240
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-LFBGA
Supplier Device Package	484-MBGA (15x15)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5cefa7m15c7n

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# **Cyclone V Device Overview**

The Cyclone<sup>®</sup> V devices are designed to simultaneously accommodate the shrinking power consumption, cost, and time-to-market requirements; and the increasing bandwidth requirements for high-volume and cost-sensitive applications.

Enhanced with integrated transceivers and hard memory controllers, the Cyclone V devices are suitable for applications in the industrial, wireless and wireline, military, and automotive markets.

#### **Related Information**

Cyclone V Device Handbook: Known Issues Lists the planned updates to the Cyclone V Device Handbook chapters.

# **Key Advantages of Cyclone V Devices**

#### Table 1. Key Advantages of the Cyclone V Device Family

Advantage	Supporting Feature
Lower power consumption	<ul> <li>Built on TSMC's 28 nm low-power (28LP) process technology and includes an abundance of hard intellectual property (IP) blocks</li> <li>Up to 40% lower power consumption than the previous generation device</li> </ul>
Improved logic integration and differentiation capabilities	<ul> <li>8-input adaptive logic module (ALM)</li> <li>Up to 13.59 megabits (Mb) of embedded memory</li> <li>Variable-precision digital signal processing (DSP) blocks</li> </ul>
Increased bandwidth capacity	<ul><li>3.125 gigabits per second (Gbps) and 6.144 Gbps transceivers</li><li>Hard memory controllers</li></ul>
Hard processor system (HPS) with integrated Arm* Cortex*-A9 MPCore* processor	<ul> <li>Tight integration of a dual-core Arm Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Cyclone V system-on-a-chip (SoC)</li> <li>Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric</li> </ul>
Lowest system cost	<ul> <li>Requires only two core voltages to operate</li> <li>Available in low-cost wirebond packaging</li> <li>Includes innovative features such as Configuration via Protocol (CvP) and partial reconfiguration</li> </ul>

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# **Summary of Cyclone V Features**

## Table 2. Summary of Features for Cyclone V Devices

Feature		Description					
Technology	<ul> <li>TSMC's 28-nm low-power (28LP) process technology</li> <li>1.1 V core voltage</li> </ul>						
Packaging	<ul> <li>Multiple device densi different device dens</li> </ul>	<ul> <li>Multiple device densities with compatible package footprints for seamless migration between different device densities</li> </ul>					
High-performance FPGA fabric	Enhanced 8-input ALM w	vith four registers					
Internal memory blocks		b) memory blocks with soft error correction code (ECC) block (MLAB)—640-bit distributed LUTRAM where you can use up to 25% memory					
Embedded Hard IP blocks	Variable-precision DSP	<ul> <li>Native support for up to three signal processing precision levels (three 9 x 9, two 18 x 18, or one 27 x 27 multiplier) in the same variable-precision DSP block</li> <li>64-bit accumulator and cascade</li> <li>Embedded internal coefficient memory</li> <li>Preadder/subtractor for improved efficiency</li> </ul>					
	Memory controller DDR3, DDR2, and LPDDR2 with 16 and 32 bit ECC support						
	Embedded transceiver I/O	PCI Express* (PCIe*) Gen2 and Gen1 (x1, x2, or x4) hard IP with multifunction support, endpoint, and root port					
Clock networks	, , , ,	l clock network d peripheral clock networks are not used can be powered down to reduce dynamic power					
Phase-locked loops (PLLs)	<ul><li> Precision clock synth</li><li> Integer mode and fra</li></ul>	esis, clock delay compensation, and zero delay buffering (ZDB) actional mode					
FPGA General-purpose I/Os (GPIOs)	<ul><li>400 MHz/800 Mbps e</li><li>On-chip termination</li></ul>	cond (Mbps) LVDS receiver and 840 Mbps LVDS transmitter external memory interface (OCT) p to 16 mA drive strength					
Low-power high-speed serial interface	Transmit pre-emphase	ibps integrated transceiver speed sis and receiver equalization nfiguration of individual channels					
HPS (Cyclone V SE, SX, and ST devices only)	<ul> <li>Single or dual-core Arm Cortex-A9 MPCore processor-up to 925 MHz maximum frequency with support for symmetric and asymmetric multiprocessing</li> <li>Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, controller area network (CAN), serial peripheral interface (SPI), I<sup>2</sup>C interface, and up to 85 HPS GPIO interfaces</li> </ul>						
		-general-purpose timers, watchdog timers, direct memory access (DMA) iguration manager, and clock and reset managers					
		continued					

<sup>&</sup>lt;sup>(1)</sup> Contact Intel for availability.



Feature	Description
	<ul> <li>HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa</li> <li>FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller</li> <li>Arm CoreSight<sup>™</sup> JTAG debug access port, trace port, and on-chip trace storage</li> </ul>
Configuration	<ul> <li>Tamper protection—comprehensive design protection to protect your valuable IP investments</li> <li>Enhanced advanced encryption standard (AES) design security features</li> <li>CvP</li> <li>Dynamic reconfiguration of the FPGA</li> <li>Active serial (AS) x1 and x4, passive serial (PS), JTAG, and fast passive parallel (FPP) x8 and x16 configuration options</li> <li>Internal scrubbing <sup>(2)</sup></li> <li>Partial reconfiguration <sup>(3)</sup></li> </ul>

# **Cyclone V Device Variants and Packages**

### Table 3. Device Variants for the Cyclone V Device Family

Variant	Description
Cyclone V E	Optimized for the lowest system cost and power requirement for a wide spectrum of general logic and DSP applications
Cyclone V GX	Optimized for the lowest cost and power requirement for 614 Mbps to 3.125 Gbps transceiver applications
Cyclone V GT	The FPGA industry's lowest cost and lowest power requirement for 6.144 Gbps transceiver applications
Cyclone V SE	SoC with integrated Arm-based HPS
Cyclone V SX	SoC with integrated Arm-based HPS and 3.125 Gbps transceivers
Cyclone V ST	SoC with integrated Arm-based HPS and 6.144 Gbps transceivers

## Cyclone V E

This section provides the available options, maximum resource counts, and package plan for the Cyclone V E devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Product Selector Guide.

#### **Related Information**

#### Product Selector Guide

Provides the latest information about Intel products.

<sup>(2)</sup> The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

<sup>(3)</sup> The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel<sup>®</sup> sales representatives.



#### **Related Information**

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices Provides the number of LVDS channels in each device package.

#### **Package Plan**

#### Table 5. Package Plan for Cyclone V E Devices

Member Code	M383 (13 mm)	M484 (15 mm)	U324 (15 mm)	F256 (17 mm)	U484 (19 mm)	F484 (23 mm)	F672 (27 mm)	F896 (31 mm)
	GPIO							
A2	223	-	176	128	224	224	-	_
A4	223	-	176	128	224	224	-	_
A5	175	-	_	_	224	240	-	_
A7	-	240	_	_	240	240	336	480
A9	-	-	-	_	240	224	336	480

# **Cyclone V GX**

This section provides the available options, maximum resource counts, and package plan for the Cyclone V GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

#### **Related Information**

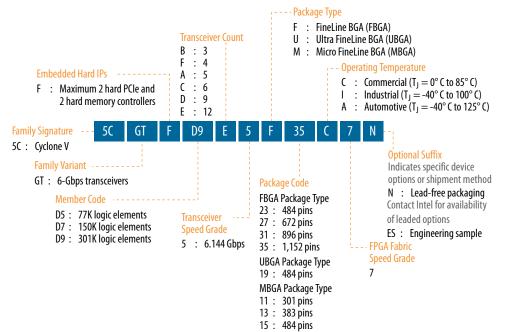
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## **Available Options**

### Figure 3. Sample Ordering Code and Available Options for Cyclone V GT Devices



#### **Maximum Resources**

#### Table 8. Maximum Resource Counts for Cyclone V GT Devices

Re	source		Member Code	
		D5	D7	D9
Logic Elements (LE) (	К)	77	150	301
ALM		29,080	56,480	113,560
Register		116,320	225,920	454,240
Memory (Kb)	M10K	4,460	6,860	12,200
	MLAB	424	836	1,717
Variable-precision DS	P Block	150	156	342
18 x 18 Multiplier		300	312	684
PLL		6	7	8
6 Gbps Transceiver		6	9	12
GPIO <sup>(5)</sup>		336 480		560
LVDS Transmitter		84	120	140
				continued

<sup>&</sup>lt;sup>(5)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.



Resource		Member Code				
		D5	D7	D9		
Receiver		84	120	140		
PCIe Hard IP Block		2	2	2		
Hard Memory Controller		2	2	2		

### **Related Information**

# True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

## **Package Plan**

#### Table 9.Package Plan for Cyclone V GT Devices

Transceiver counts shown are for transceiver  $\leq 5$  Gbps . 6 Gbps transceiver channel count support depends on the package and channel usage. For more information about the 6 Gbps transceiver channel count, refer to the *Cyclone V Device Handbook Volume 2: Transceivers*.

Member Code	M3 (11 )		M383 (13 mm)		M484 (15 mm)		U484 (19 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
D5	129	4	175	6	_	_	224	6
D7	_	_	_	_	240	3	240	6
D9	—	—	—	_	—		240	5

Member Code	F484 (23 mm)				F6 (27 i		F8 (31	96 mm)	F11 (35 i	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR		
D5	240	6	336	6	_	_	_	_		
D7	240	6	336	9 ( <del>6</del> )	480	9 ( <del>6</del> )	—	—		
D9	224	6	336	9 ( <del>6</del> )	480	12 (7)	560	12 (7)		

#### **Related Information**

6.144-Gbps Support Capability in Cyclone V GT Devices, Cyclone V Device Handbook Volume 2: Transceivers

Provides more information about 6 Gbps transceiver channel count.

<sup>(6)</sup> If you require CPRI (at 6.144 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to three full-duplex transceiver channels for CPRI, and up to six full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.

<sup>(7)</sup> If you require CPRI (at 6.144 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to three full-duplex transceiver channels for CPRI, and up to eight full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.



## **Cyclone V SE**

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SE devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

#### **Related Information**

#### Product Selector Guide

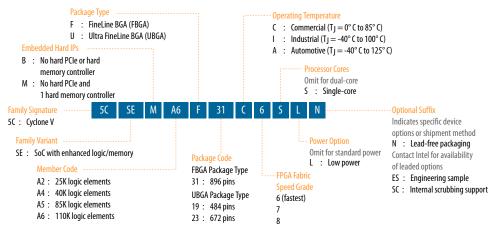
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### **Available Options**

#### Figure 4. Sample Ordering Code and Available Options for Cyclone V SE Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.





## **Maximum Resources**

#### Table 10. Maximum Resource Counts for Cyclone V SE Devices

Res	ource		Ме	mber Code	
		A2	A4	A5	A6
Logic Elements (	LE) (K)	25	40	85	110
ALM		9,430	15,880	32,070	41,910
Register		37,736	60,376	128,300	166,036
Memory (Kb)	M10K	1,400	2,700	3,970	5,570
	MLAB	138	231	480	621
Variable-precisio	n DSP Block	36	84	87	112
18 x 18 Multiplie	r	72	168	174	224
FPGA PLL		5	5	6	6
HPS PLL		3	3	3	3
FPGA GPIO		145	145	288	288
HPS I/O		181	181	181	181
LVDS	Transmitter	32	32	72	72
	Receiver		37	72	72
FPGA Hard Memo	ory Controller	1	1	1	1
HPS Hard Memor	y Controller	1	1	1	1
Arm Cortex-A9 M	IPCore Processor	Single- or dual- core	Single- or dual- core	Single- or dual-core	Single- or dual-core

#### **Related Information**

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices Provides the number of LVDS channels in each device package.

## **Package Plan**

#### Table 11.Package Plan for Cyclone V SE Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U484 (19 mm)		U6 (23 I		F896 (31 mm)	
	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O
A2	66	151	145	181	_	_
A4	66	151	145	181	_	_
A5	66	151	145	181	288	181
A6	66	151	145	181	288	181





## **Cyclone V SX**

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

#### **Related Information**

#### Product Selector Guide

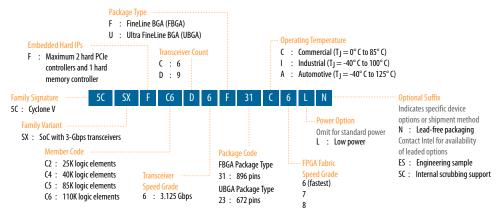
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## **Available Options**

#### Figure 5. Sample Ordering Code and Available Options for Cyclone V SX Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.



#### **Maximum Resources**

#### Table 12. Maximum Resource Counts for Cyclone V SX Devices

Resource			Member Code				
		C2	C4	C5	C6		
Logic Elements (LE) (K)		25	40	85	110		
ALM		9,430	15,880	32,070	41,910		
Register		37,736	60,376	128,300	166,036		
Memory (Kb)	M10K	1,400	2,700	3,970	5,570		
	MLAB	138	231	480	621		
Variable-precision D	SP Block	36	84	87	112		
18 x 18 Multiplier		72	168	174	224		
FPGA PLL		5	5	6	6		
			•		continued.		

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F	Resource		Member Code				
		C2	C4	C5	C6		
HPS PLL		3	3	3	3		
3 Gbps Transce	iver	6	6	9	9		
FPGA GPIO <sup>(8)</sup>		145	145	288	288		
HPS I/O		181	181	181	181		
LVDS	Transmitter	32	32	72	72		
	Receiver	37	37	72	72		
PCIe Hard IP Bl	lock	2	2	2 <sup>(9)</sup>	2 (9)		
FPGA Hard Memory Controller		1	1	1	1		
HPS Hard Memory Controller		1	1	1	1		
Arm Cortex-A9	MPCore Processor	Dual-core	Dual-core	Dual-core	Dual-core		

#### **Related Information**

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices Provides the number of LVDS channels in each device package.

## **Package Plan**

### Table 13.Package Plan for Cyclone V SX Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U672 (23 mm)			F896 (31 mm)		
	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR
C2	145	181	6	_	_	_
C4	145	181	6	_	_	_
C5	145	181	6	288	181	9
C6	145	181	6	288	181	9

# **Cyclone V ST**

This section provides the available options, maximum resource counts, and package plan for the Cyclone V ST devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

<sup>&</sup>lt;sup>(8)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>&</sup>lt;sup>(9)</sup> 1 PCIe Hard IP Block in U672 package.



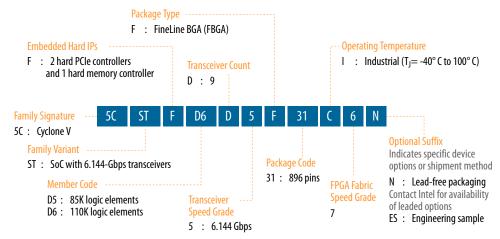
### **Related Information**

Product Selector Guide

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## **Available Options**

### Figure 6. Sample Ordering Code and Available Options for Cyclone V ST Devices



## **Maximum Resources**

### Table 14. Maximum Resource Counts for Cyclone V ST Devices

Res	ource	Member	r Code
		D5	D6
Logic Elements (LE) (K)		85	110
ALM		32,070	41,910
Register		128,300	166,036
Memory (Kb)	M10K	3,970	5,570
	MLAB	480	621
Variable-precision DSP Block		87	112
18 x 18 Multiplier		174	224
FPGA PLL		6	6
HPS PLL		3	3
6.144 Gbps Transceiver		9	9
FPGA GPIO <sup>(10)</sup>		288	288
HPS I/O		181	181
LVDS	Transmitter	72	72
	-		continued

<sup>&</sup>lt;sup>(10)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

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Resource		Member Code		
		D5	D6	
Receiver		72	72	
PCIe Hard IP Block		2	2	
FPGA Hard Memory Controller		1	1	
HPS Hard Memory Controller		1	1	
Arm Cortex-A9 MPCore Processor		Dual-core	Dual-core	

#### **Related Information**

# True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

## **Package Plan**

#### Table 15. Package Plan for Cyclone V ST Devices

- The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPSspecific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.
- Transceiver counts shown are for transceiver ≤5 Gbps . 6 Gbps transceiver channel count support depends on the package and channel usage. For more information about the 6 Gbps transceiver channel count, refer to the Cyclone V Device Handbook Volume 2: Transceivers.

Member Code	F896 (31 mm)				
	FPGA GPIO	HPS I/O	XCVR		
D5	288	181	9 (11)		
D6	288	181	9 (11)		

### **Related Information**

6.144-Gbps Support Capability in Cyclone V GT Devices, Cyclone V Device Handbook Volume 2: Transceivers

Provides more information about 6 Gbps transceiver channel count.

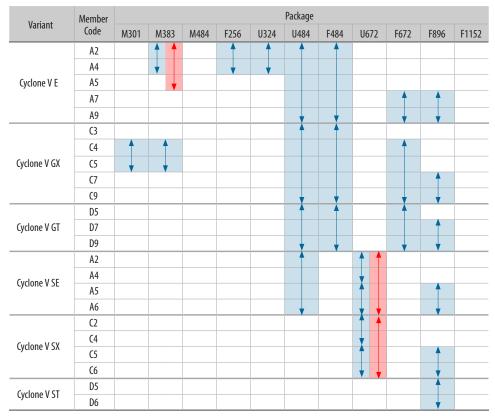
<sup>(11)</sup> If you require CPRI (at 4.9152 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to seven full-duplex transceiver channels for CPRI, and up to six full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.



# **I/O Vertical Migration for Cyclone V Devices**

#### Figure 7. Vertical Migration Capability Across Cyclone V Device Packages and Densities

The arrows indicate the vertical migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



You can achieve the vertical migration shaded in red if you use only up to 175 GPIOs for the M383 package, and 138 GPIOs for the U672 package. These migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

*Note:* To verify the pin migration compatibility, use the Pin Migration View window in the Intel Quartus Prime software Pin Planner.

# **Adaptive Logic Module**

Cyclone V devices use a 28 nm ALM as the basic building block of the logic fabric.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.



Variant	Member Code			18 x 18 Multiplier Adder Mode	18 x 18 Multiplier Adder		
		DSP BIOCK	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	Adder Mode	Summed with 36 bit Input
	C6	112	336	224	112	112	112
Cyclone V ST	D5	87	261	174	87	87	87
	D6	112	336	224	112	112	112

# **Embedded Memory Blocks**

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.

# **Types of Embedded Memory**

The Cyclone V devices contain two types of memory blocks:

- 10 Kb M10K blocks—blocks of dedicated memory resources. The M10K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Cyclone V devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

# **Embedded Memory Capacity in Cyclone V Devices**

## Table 18. Embedded Memory Capacity and Distribution in Cyclone V Devices

	Momber	Member M10K		ML	Total RAM Bit	
Variant	Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	(Kb)
Cyclone V E	A2	176	1,760	314	196	1,956
	A4	308	3,080	485	303	3,383
	A5	446	4,460	679	424	4,884
	A7	686	6,860	1338	836	7,696
	A9	1,220	12,200	2748	1,717	13,917
Cyclone V GX	C3	135	1,350	291	182	1,532
	C4	250	2,500	678	424	2,924
	C5	446	4,460	678	424	4,884
	C7	686	6,860	1338	836	7,696
	C9	1,220	12,200	2748	1,717	13,917
						continued



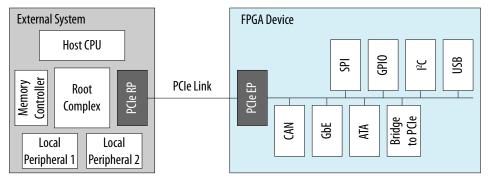
# PCIe Gen1 and Gen2 Hard IP

Cyclone V GX, GT, SX, and ST devices contain PCIe hard IP that is designed for performance and ease-of-use. The PCIe hard IP consists of the MAC, data link, and transaction layers.

The PCIe hard IP supports PCIe Gen2 and Gen1 end point and root port for up to x4 lane configuration. The PCIe Gen2 x4 support is PCIe-compatible.

The PCIe endpoint support includes multifunction support for up to eight functions, as shown in the following figure. The integrated multifunction support reduces the FPGA logic requirements by up to 20,000 LEs for PCIe designs that require multiple peripherals.

#### Figure 9. PCIe Multifunction for Cyclone V Devices



The Cyclone V PCIe hard IP operates independently from the core logic. This independent operation allows the PCIe link to wake up and complete link training in less than 100 ms while the Cyclone V device completes loading the programming file for the rest of the device.

In addition, the PCIe hard IP in the Cyclone V device provides improved end-to-end datapath protection using ECC.

# **External Memory Interface**

This section provides an overview of the external memory interface in Cyclone V devices.

## Hard and Soft Memory Controllers

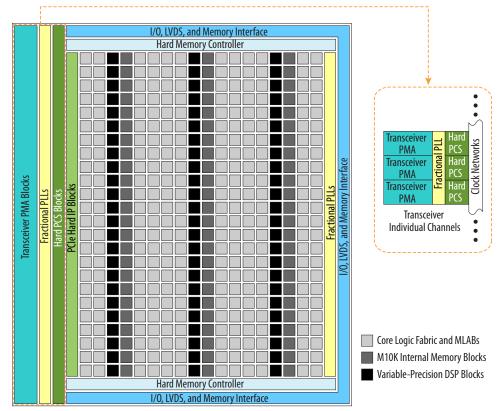
Cyclone V devices support up to two hard memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices. Each controller supports 8 to 32 bit components of up to 4 gigabits (Gb) in density with two chip selects and optional ECC. For the Cyclone V SoC devices, an additional hard memory controller in the HPS supports DDR3, DDR2, and LPDDR2 SDRAM devices.

All Cyclone V devices support soft memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices for maximum flexibility.



#### Figure 10. Device Chip Overview for Cyclone V GX and GT Devices

The figure shows a Cyclone V FPGA with transceivers. Different Cyclone V devices may have a different floorplans than the one shown here.



## **PMA Features**

To prevent core and I/O noise from coupling into the transceivers, the PMA block is isolated from the rest of the chip—ensuring optimal signal integrity. For the transceivers, you can use the channel PLL of an unused receiver PMA as an additional transmit PLL.

#### Table 22. PMA Features of the Transceivers in Cyclone V Devices

Features	Capability
Backplane support	Driving capability up to 6.144 Gbps
PLL-based clock recovery	Superior jitter tolerance
Programmable deserialization and word alignment	Flexible deserialization width and configurable word alignment pattern
Equalization and pre-emphasis	<ul> <li>Up to 14.37 dB of pre-emphasis and up to 4.7 dB of equalization</li> <li>No decision feedback equalizer (DFE)</li> </ul>
Ring oscillator transmit PLLs	614 Mbps to 6.144 Gbps
Input reference clock range	20 MHz to 400 MHz
Transceiver dynamic reconfiguration	Allows the reconfiguration of a single channel without affecting the operation of other channels



## **PCS Features**

The Cyclone V core logic connects to the PCS through an 8, 10, 16, 20, 32, or 40 bit interface, depending on the transceiver data rate and protocol. Cyclone V devices contain PCS hard IP to support PCIe Gen1 and Gen2, Gbps Ethernet (GbE), Serial RapidIO<sup>®</sup> (SRIO), and Common Public Radio Interface (CPRI).

Most of the standard and proprietary protocols from 614 Mbps to 6.144 Gbps are supported.

Table 23.	<b>Transceiver PCS</b>	Features for C	vclone V Devices
		i cutui co i ci c	

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
3-Gbps and 6-Gbps Basic	0.614 to 6.144	<ul> <li>Phase compensation FIFO</li> <li>Byte serializer</li> <li>8B/10B encoder</li> <li>Transmitter bit-slip</li> </ul>	<ul> <li>Word aligner</li> <li>Deskew FIFO</li> <li>Rate-match FIFO</li> <li>8B/10B decoder</li> <li>Byte deserializer</li> <li>Byte ordering</li> <li>Receiver phase compensation FIFO</li> </ul>
PCIe Gen1 (x1, x2, x4)	2.5 and 5.0	<ul> <li>Dedicated PCIe PHY IP core</li> <li>PIPE 2.0 interface to the core</li> </ul>	<ul> <li>Dedicated PCIe PHY IP core</li> <li>PIPE 2.0 interface to the core logic</li> </ul>
PCIe Gen2 ( x1, x2, x4) <sup>(12)</sup>		logic	logic
GbE	1.25	<ul> <li>Custom PHY IP core with preset feature</li> <li>GbE transmitter synchronization state machine</li> </ul>	<ul> <li>Custom PHY IP core with preset feature</li> <li>GbE receiver synchronization state machine</li> </ul>
XAUI (13)	3.125	Dedicated XAUI PHY IP core	Dedicated XAUI PHY IP core
HiGig	3.75	XAUI synchronization state machine for bonding four channels	XAUI synchronization state machine for realigning four channels
SRIO 1.3 and 2.1	1.25 to 3.125	<ul> <li>Custom PHY IP core with preset feature</li> <li>SRIO version 2.1-compliant x2 and x4 channel bonding</li> </ul>	<ul> <li>Custom PHY IP core with preset feature</li> <li>SRIO version 2.1-compliant x2 and x4 deskew state machine</li> </ul>
SDI, SD/HD, and 3G-SDI	0.27 <sup>(14)</sup> , 1.485, and 2.97	Custom PHY IP core with preset feature	Custom PHY IP core with preset feature
JESD204A	0.3125 <sup>(15)</sup> to 3.125		
	•	•	continued

<sup>&</sup>lt;sup>(12)</sup> PCIe Gen2 is supported for Cyclone V GT and ST devices. The PCIe Gen2 x4 support is PCIe-compatible.

- <sup>(13)</sup> XAUI is supported through the soft PCS.
- $^{(14)}$  The 0.27-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.
- <sup>(15)</sup> The 0.3125-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.



Apart from lowering cost and power consumption, partial reconfiguration increases the effective logic density of the device because placing device functions that do not operate simultaneously is not necessary. Instead, you can store these functions in external memory and load them whenever the functions are required. This capability reduces the size of the device because it allows multiple applications on a single device—saving the board space and reducing the power consumption.

Intel simplifies the time-intensive task of partial reconfiguration by building this capability on top of the proven incremental compile and design flow in the Intel Quartus Prime design software. With the Intel solution, you do not need to know all the intricate device architecture details to perform a partial reconfiguration.

Partial reconfiguration is supported through the FPP x16 configuration interface. You can seamlessly use partial reconfiguration in tandem with dynamic reconfiguration to enable simultaneous partial reconfiguration of both the device core and transceivers.

# **Enhanced Configuration and Configuration via Protocol**

Cyclone V devices support 1.8 V, 2.5 V, 3.0 V, and 3.3 V programming voltages and several configuration schemes.

Mode	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps)	Decompressi on	Design Security	Partial Reconfigurat ion <sup>(18)</sup>	Remote System Update
AS through the EPCS and EPCQ serial configuration device	1 bit, 4 bits	100	_	Yes	Yes	_	Yes
PS through CPLD or external microcontroller	1 bit	125	125	Yes	Yes	_	_
FPP	8 bits	125	_	Yes	Yes	-	Parallel flash loader
	16 bits	125	_	Yes	Yes	Yes	
CvP (PCIe)	x1, x2, and x4 lanes	-	-	Yes	Yes	Yes	_
JTAG	1 bit	33	33	-	_	-	_

 Table 24.
 Configuration Schemes and Features Supported by Cyclone V Devices

Instead of using an external flash or ROM, you can configure the Cyclone V devices through PCIe using CvP. The CvP mode offers the fastest configuration rate and flexibility with the easy-to-use PCIe hard IP block interface. The Cyclone V CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

## **Related Information**

Configuration via Protocol (CvP) Implementation in Intel FPGAs User Guide Provides more information about CvP.

<sup>&</sup>lt;sup>(18)</sup> The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

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Date	Version	Changes	
		<ul> <li>Updated Figure 1, Figure 2, Figure 3, Figure 4, Figure 5, Figure 6, and Figure 10.</li> <li>Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections.</li> <li>Text edits throughout the document.</li> </ul>	
February 2012	1.2	<ul> <li>Updated Table 1–2, Table 1–3, and Table 1–6.</li> <li>Updated "Cyclone V Family Plan" on page 1–4 and "Clock Networks and PLL Clock Sources" on page 1–15.</li> <li>Updated Figure 1–1 and Figure 1–6.</li> </ul>	
November 2011	1.1	<ul> <li>Updated Table 1–1, Table 1–2, Table 1–3, Table 1–4, Table 1–5, and Table 1–6.</li> <li>Updated Figure 1–4, Figure 1–5, Figure 1–6, Figure 1–7, and Figure 1–8.</li> <li>Updated "System Peripherals" on page 1–18, "HPS-FPGA AXI Bridges" on page 1–19, "HPS SDRAM Controller Subsystem" on page 1–19, "FPGA Configuration and Processor Booting" on page 1–19, and "Hardware and Software Development" on page 1–20.</li> <li>Minor text edits.</li> </ul>	
October 2011	1.0	Initial release.	